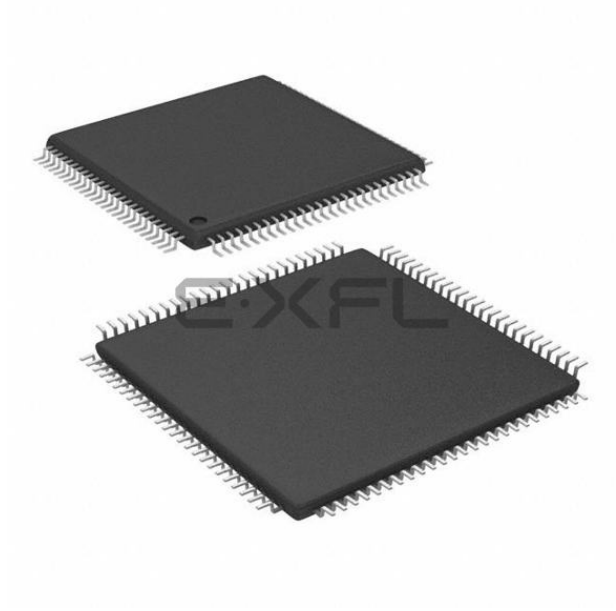

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

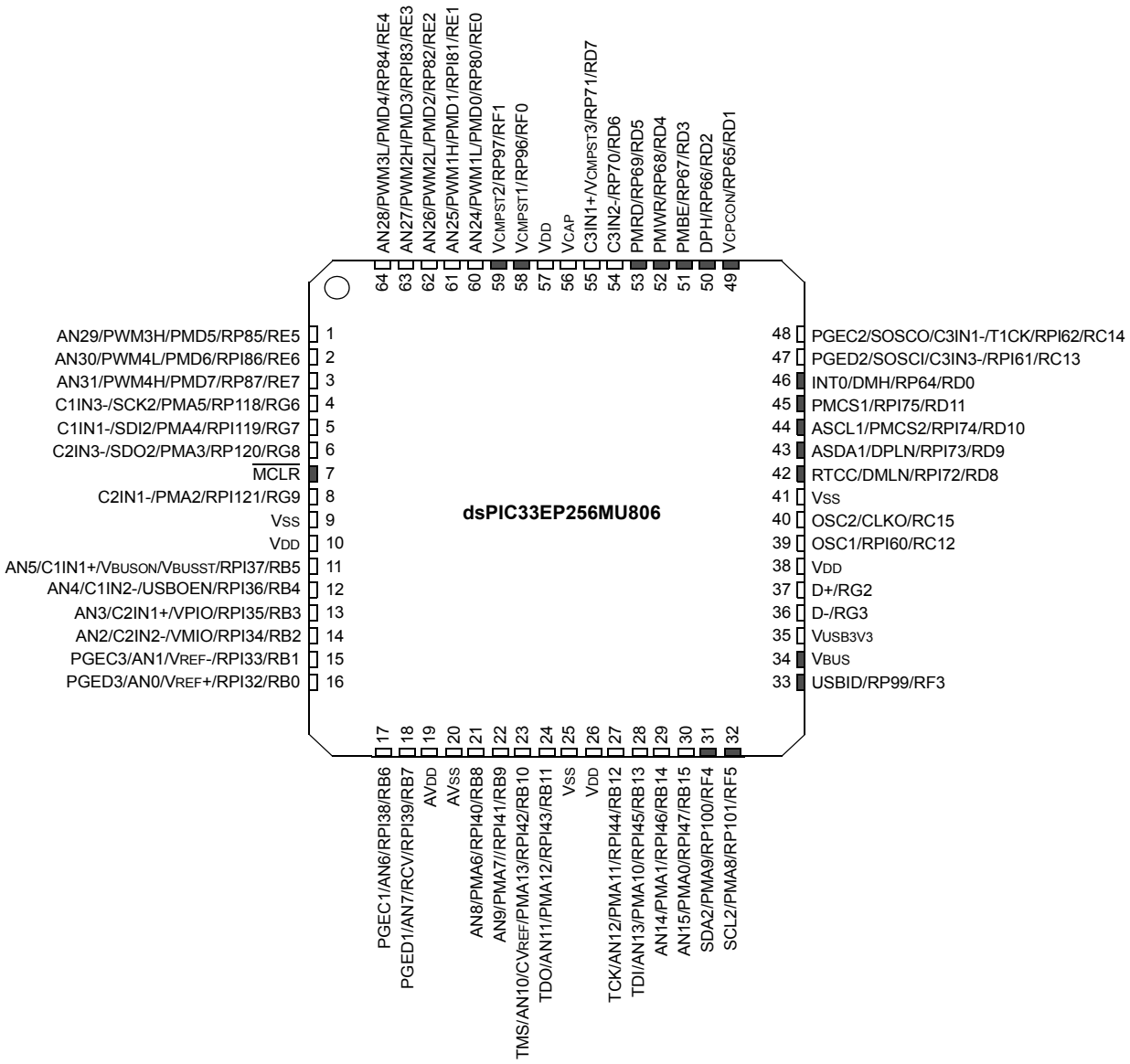
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	83
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 32x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512gu810-i-pf

Pin Diagrams

64-Pin QFN

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select"** for available peripherals and for information on limitations.

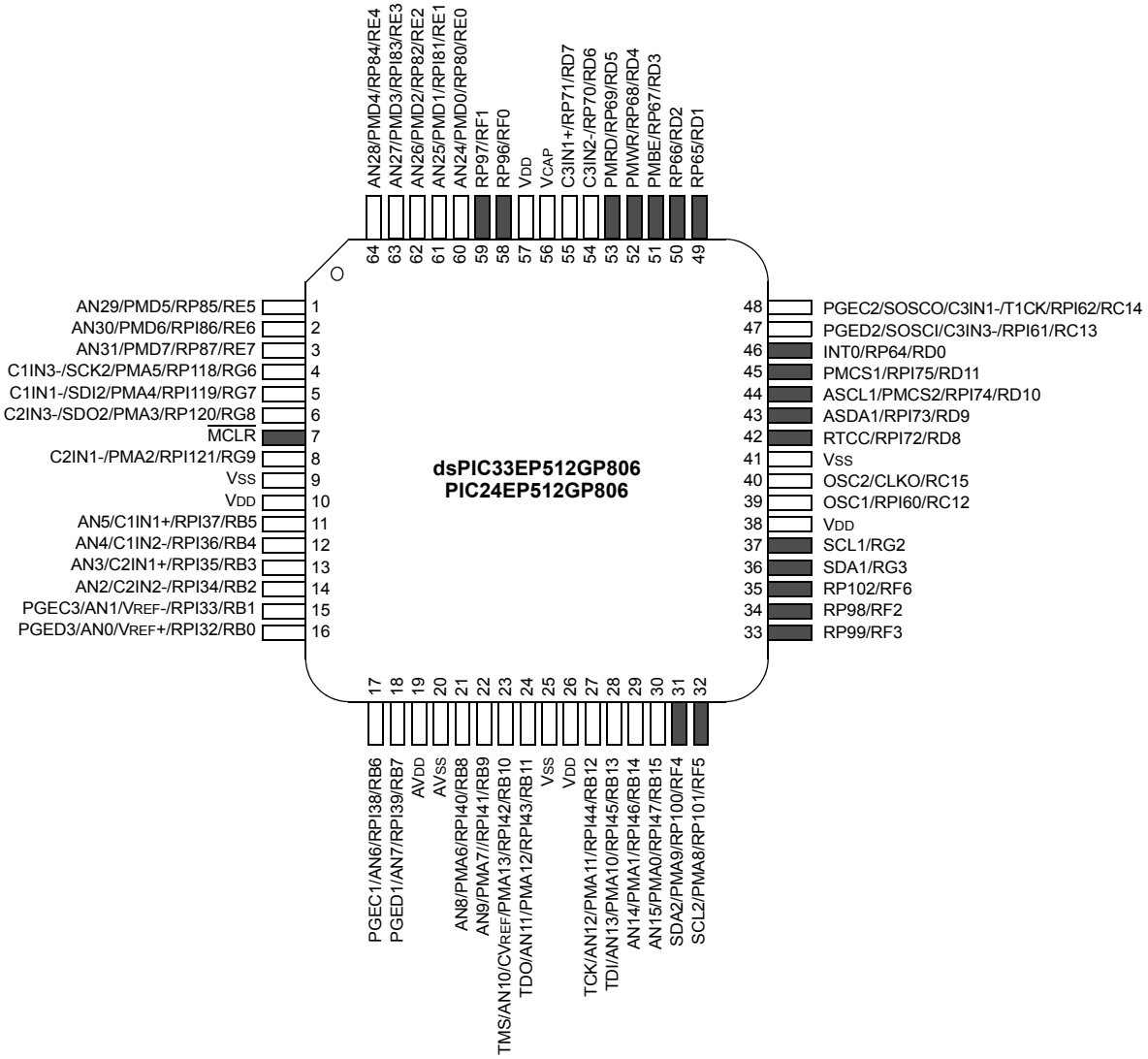
2: Every I/O port pin (RAx-RGx) can be used as change notification (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The availability of I^2C™ interfaces varies by device. Selection (SDAx/SCLx or ASDAx/ASCLx) is made using the device Configuration bits, ALTI2C1 and ALTI2C2 (FPOR<5:4>). See **Section 29.0 "Special Features"** for more information.

Pin Diagrams (Continued)

64-Pin TQFP

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as change notification (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The availability of I^2C™ interfaces varies by device. Selection (SDAx/SCLx or ASDAx/ASCLx) is made using the device Configuration bits, ALTI2C1 and ALTI2C2 (FPOR<5:4>). See **Section 29.0 "Special Features"** for more information.

3.8 Arithmetic Logic Unit (ALU)

The ALU is 16 bits wide and is capable of addition, subtraction, bit shifts and logic operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. Depending on the operation, the ALU can affect the values of the Carry (C), Zero (Z), Negative (N), Overflow (OV) and Digit Carry (DC) Status bits in the SR register. The C and DC Status bits operate as Borrow and Digit Borrow bits, respectively, for subtraction operations.

The ALU can perform 8-bit or 16-bit operations, depending on the mode of the instruction that is used. Data for the ALU operation can come from the W register array or data memory, depending on the addressing mode of the instruction. Likewise, output data from the ALU can be written to the W register array or a data memory location.

Refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157) for information on the SR bits affected by each instruction.

The core CPU incorporates hardware support for both multiplication and division. This includes a dedicated hardware multiplier and support hardware for 16-bit divisor division.

3.8.1 MULTIPLIER

Using the high-speed 17-bit x 17-bit multiplier, the ALU supports unsigned, signed, or mixed-sign operation in several MCU multiplication modes:

- 16-bit x 16-bit signed
- 16-bit x 16-bit unsigned
- 16-bit signed x 5-bit (literal) unsigned
- 16-bit signed x 16-bit unsigned
- 16-bit unsigned x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit signed
- 8-bit unsigned x 8-bit unsigned

3.8.2 DIVIDER

The divide block supports 32-bit/16-bit and 16-bit/16-bit signed and unsigned integer divide operations with the following data sizes:

1. 32-bit signed/16-bit signed divide
2. 32-bit unsigned/16-bit unsigned divide
3. 16-bit signed/16-bit signed divide
4. 16-bit unsigned/16-bit unsigned divide

The quotient for all divide instructions ends up in W0 and the remainder in W1. The 16-bit signed and unsigned `DIV` instructions can specify any W register for both the 16-bit divisor (Wn) and any W register (aligned) pair (W(m + 1):Wm) for the 32-bit dividend. The divide algorithm takes one cycle per bit of divisor, so both 32-bit/16-bit and 16-bit/16-bit instructions take the same number of cycles to execute.

3.9 DSP Engine (dsPIC33EPXXX(GP/MC/MU)806/810/814 Devices Only)

The DSP engine consists of a high-speed 17-bit x 17-bit multiplier, a 40-bit barrel shifter and a 40-bit adder/subtracter (with two target accumulators, round and saturation logic).

The DSP engine can also perform inherent accumulator-to-accumulator operations that require no additional data. These instructions are: `ADD`, `SUB` and `NEG`.

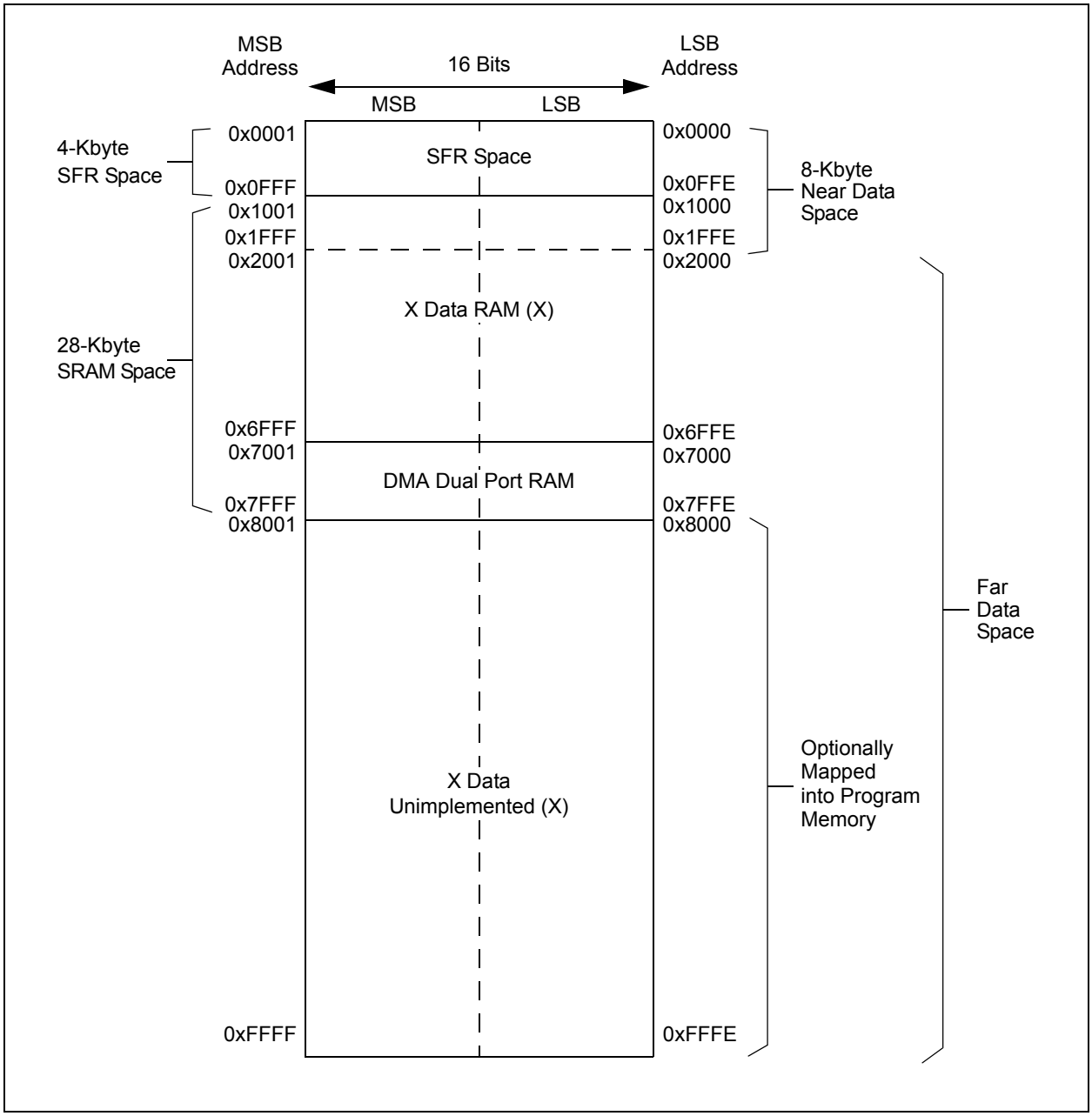
The DSP engine has options selected through bits in the CPU Core Control register (CORCON), as listed below:

- Fractional or integer DSP multiply (IF)
- Signed, unsigned or mixed-sign DSP multiply (US)
- Conventional or convergent rounding (RND)
- Automatic saturation on/off for ACCA (SATA)
- Automatic saturation on/off for ACCB (SATB)
- Automatic saturation on/off for writes to data memory (SATDW)
- Accumulator Saturation mode selection (ACCSAT)

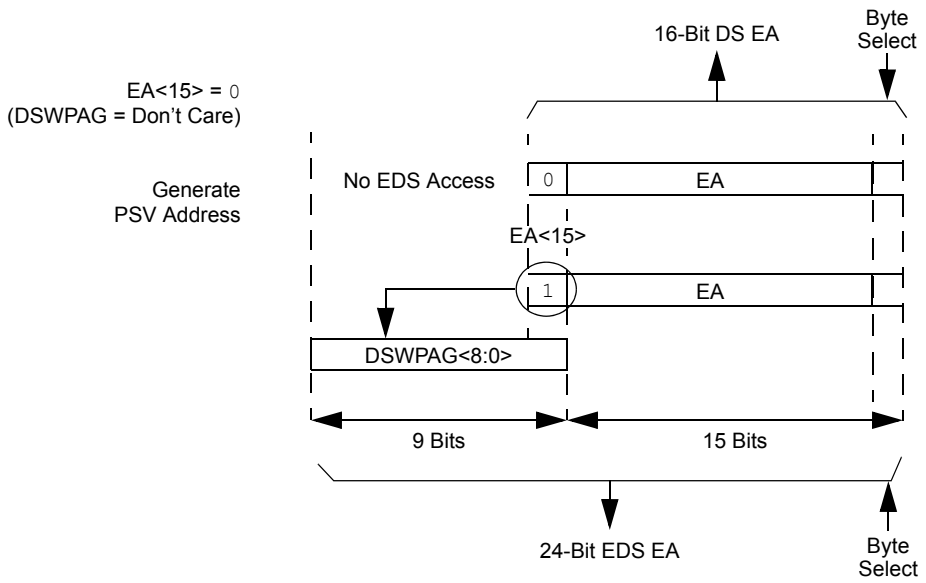
TABLE 3-2: DSP INSTRUCTIONS SUMMARY

Instruction	Algebraic Operation	ACC Write Back
CLR	$A = 0$	Yes
ED	$A = (x - y)^2$	No
EDAC	$A = A + (x - y)^2$	No
MAC	$A = A + (x \bullet y)$	Yes
MAC	$A = A + x^2$	No
MOVSAC	No change in A	Yes
MPY	$A = x \bullet y$	No
MPY	$A = x^2$	No
MPY.N	$A = -x \bullet y$	No
MSC	$A = A - x \bullet y$	Yes

FIGURE 4-6: DATA MEMORY MAP FOR PIC24EP256GU810/814 DEVICES WITH 28-KBYTE RAM



EXAMPLE 4-2: EXTENDED DATA SPACE (EDS) WRITE ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

The paged memory scheme provides access to multiple 32-Kbyte windows in the EDS and PSV memory. The Data Space Page registers DSxPAG, in combination with the upper half of data space address can provide up to 16 Mbytes of additional address space in the EDS and 12 Mbytes (DSRPAG only) of PSV address space. The paged data memory space is shown in Example 4-3.

The Program Space (PS) can be accessed with DSRPAG of 0x200 or greater. Only reads from PS are supported using the DSRPAG. Writes to PS are not supported, so DSWPAG is dedicated to DS, including EDS, only. The data space and EDS can be read from and written to using DSRPAG and DSWPAG, respectively.

REGISTER 7-1: SR: CPU STATUS REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/C-0	R/C-0	R-0	R/W-0
OA	OB	SA	SB	OAB	SAB	DA	DC
bit 15							bit 8

R/W-0(3)	R/W-0(3)	R/W-0(3)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL<2:0>(2)			RA	N	OV	Z	C
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)

111 = CPU Interrupt Priority Level is 7 (15, user interrupts are disabled)
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

Note 1: For complete register details, see **Register 3-1: "SR: CPU Status Register"**.

2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = 1.

3: The IPL<2:0> Status bits are read-only when NSTDIS (INTCON1<15>) = 1.

11.4.4.2 Virtual Connections

The dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 devices support virtual (internal) connections to the output of the comparator modules, CMP1OUT, CMP2OUT and CMP3OUT (see Figure 25-1 in **Section 25.0 "Comparator Module"**). In addition, dsPIC33EPXXXMU806/810/814 devices support virtual connections to the filtered QEI module inputs, FINDX1, FHOME1, FINDX2 and FHOME2 (see Figure 17-1 in **Section 17.0 "Quadrature Encoder Interface (QEI) Module (dsPIC33EPXXX(MC/MU)8XX Devices Only)"**.

Virtual connections provide a simple way of inter-peripheral connection without utilizing a physical pin. For example, by setting the FLT1R<6:0> bits of the RPINR12 register to the value of 'b0000001, the output of the analog comparator, CMP1OUT, will be connected to the PWM Fault 1 input, which allows the analog comparator to trigger PWM Faults without the use of an actual physical pin on the device.

Virtual connection to the QEI module allows peripherals to be connected to the QEI digital filter input. To utilize this filter, the QEI module must be enabled, and its inputs must be connected to a physical RPn/RPIn pin. Example 11-2 illustrates how the input capture module can be connected to the QEI digital filter.

11.4.4.3 Mapping Limitations

The control schema of the peripheral select pins is not limited to a small range of fixed peripheral configurations. There are no mutual or hardware enforced lockouts between any of the peripheral mapping SFRs. Literally any combination of peripheral mappings across any or all of the RPn/RPIn pins is possible. This includes both many-to-one and one-to-many mappings of peripheral inputs and outputs to pins. While such mappings may be technically possible from a configuration point of view, they may not be supportable from an electrical point of view.

EXAMPLE 11-2: CONNECTING IC1 TO HOME1 DIGITAL FILTER INPUT ON PIN 3 OF THE dsPIC33EP512MU810 DEVICE

```
RPINR15 = 0x5600;      /* Connect the QEI1 HOME1 input to RP86 (pin 3) */
RPINR7 = 0x009;        /* Connect the IC1 input to the digital filter on the FHOME1 input */

QEI1IOC = 0x4000;      /* Enable the QEI digital filter */
QEI1CON = 0x8000;      /* Enable the QEI module */
```

REGISTER 11-6: RPINR5: PERIPHERAL PIN SELECT INPUT REGISTER 5

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	T7CKR<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	T6CKR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **T7CKR<6:0>:** Assign Timer7 External Clock (T7CK) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP127
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **T6CKR<6:0>:** Assign Timer6 External Clock (T6CK) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP127
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 11-17: RPINR16: PERIPHERAL PIN SELECT INPUT REGISTER 16 (dsPIC33EPXXXMU806/810/814 DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEB2R<6:0>(1)						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEA2R<6:0>(1)						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **QEB2R<6:0>:** Assign B (QEI2) to the Corresponding RPn/RPIn Pin bits(1)
(see Table 11-2 for input pin selection numbers)
1111111 = Input tied to RP127
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **QEA2R<6:0>:** Assign A (QEI2) to the Corresponding RPn/RPIn Pin bits(1)
(see Table 11-2 for input pin selection numbers)
1111111 = Input tied to RP127
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

Note 1: These bits are available on dsPIC33EPXXX(MC/MU)806/810/814 devices only.

NOTES:

NOTES:

REGISTER 20-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)

bit 5 **ADDEN:** Address Character Detect bit (bit 8 of received data = 1)
- 1 = Address Detect mode is enabled; if 9-bit mode is not selected, this does not take effect
- 0 = Address Detect mode is disabled

bit 4 **RIDLE:** Receiver Idle bit (read-only)
- 1 = Receiver is Idle
- 0 = Receiver is active

bit 3 **PERR:** Parity Error Status bit (read-only)
- 1 = Parity error has been detected for the current character (character at the top of the receive FIFO)
- 0 = Parity error has not been detected

bit 2 **FERR:** Framing Error Status bit (read-only)
- 1 = Framing error has been detected for the current character (character at the top of the receive FIFO)
- 0 = Framing error has not been detected

bit 1 **OERR:** Receive Buffer Overrun Error Status bit (read/clear only)
- 1 = Receive buffer has overflowed
- 0 = Receive buffer has not overflowed; clearing a previously set OERR bit (1 → 0 transition) resets the receiver buffer and the UxRSR to the empty state

bit 0 **URXDA:** Receive Buffer Data Available bit (read-only)
- 1 = Receive buffer has data, at least one more character can be read
- 0 = Receive buffer is empty

Note 1: Refer to **Section 17. "UART"** (DS70582) in the *"dsPIC33E/PIC24E Family Reference Manual"* for information on enabling the UARTx module for transmit operation.

REGISTER 22-4: UxSTAT: USB STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	U-0	U-0
ENDPT<3:0>(2)				DIR	PPBI(1)	—	—
bit 7							bit 0

Legend:	U = Unimplemented bit, read as '0'		
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-4 **ENDPT<3:0>:** Last Endpoint Activity Number bits
(represents the number of the endpoint BDT updated by the last USB transfer)(2)
1111 = Endpoint 15
1110 = Endpoint 14
•
•
•
0001 = Endpoint 1
0000 = Endpoint 0

bit 3 **DIR:** Last Buffer Descriptor Direction Indicator bit
1 = The last transaction was a transmit transfer (TX)
0 = The last transaction was a receive transfer (RX)

bit 2 **PPBI:** Ping-Pong Buffer Descriptor Pointer Indicator bit(1)
1 = The last transaction was to the ODD buffer descriptor bank
0 = The last transaction was to the EVEN buffer descriptor bank

bit 1-0 **Unimplemented:** Read as '0'

Note 1: This bit is only valid for endpoints with available EVEN and ODD buffer descriptor registers.

2: In Host mode, all transactions are processed through Endpoint 0 and the Endpoint 0 BDTs. Therefore, ENDPT<3:0> will always read as '0000'.

REGISTER 22-22: UxEPn: USB ENDPOINT n CONTROL REGISTERS (n = 0 TO 15)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
LSPD(1)	RETRYDIS(1)	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **LSPD:** Low-Speed Direct Connection Enable bit (UEP0 only)(1)
1 = Direct connection to a low-speed device is enabled
0 = Direct connection to a low-speed device is disabled

bit 6 **RETRYDIS:** Retry Disable bit (UEP0 only)(1)
1 = Retry NAK transactions is disabled
0 = Retry NAK transactions is enabled; retry done in hardware

bit 5 **Unimplemented:** Read as '0'

bit 4 **EPCONDIS:** Bidirectional Endpoint Control bit
If EPTXEN and EPRXEN = 1:
1 = Disable Endpoint n from control transfers; only TX and RX transfers are allowed
0 = Enable Endpoint n for control (SETUP) transfers; TX and RX transfers are also allowed
For all other combinations of EPTXEN and EPRXEN:
This bit is ignored.

bit 3 **EPRXEN:** Endpoint Receive Enable bit
1 = Endpoint n receive is enabled
0 = Endpoint n receive is disabled

bit 2 **EPTXEN:** Endpoint Transmit Enable bit
1 = Endpoint n transmit is enabled
0 = Endpoint n transmit is disabled

bit 1 **EPSTALL:** Endpoint Stall Status bit
1 = Endpoint n was stalled
0 = Endpoint n was not stalled

bit 0 **EPHSHK:** Endpoint Handshake Enable bit
1 = Endpoint handshake is enabled
0 = Endpoint handshake is disabled (typically used for isochronous endpoints)

Note 1: These bits are available only for UxEP0 and only in Host mode. For all other UxEPn registers, these bits are always unimplemented and read as '0'.

TABLE 32-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param.(2)	**Typ.(3)**	**Max.**	**Units**	**Conditions**		
Operating Current (IDD)(1)						
DC20d	12	18	mA	-40°C	3.3V	10 MIPS
DC20a	12	18	mA	+25°C		
DC20b	13	20	mA	+85°C		
DC20c	14	21	mA	+125°C		
DC22d	23	35	mA	-40°C	3.3V	20 MIPS
DC22a	24	36	mA	+25°C		
DC22b	24	36	mA	+85°C		
DC22c	25	38	mA	+125°C		
DC24d	42	63	mA	-40°C	3.3V	40 MIPS
DC24a	43	65	mA	+25°C		
DC24b	44	66	mA	+85°C		
DC24c	45	68	mA	+125°C		
DC25d	61	92	mA	-40°C	3.3V	60 MIPS
DC25a	62	93	mA	+25°C		
DC25b	62	93	mA	+85°C		
DC25c	63	95	mA	+125°C		
DC26d	69	104	mA	-40°C	3.3V	70 MIPS
DC26a	70	105	mA	+25°C		
DC26b	70	105	mA	+85°C		

Note 1: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC Clock Overshoot/Undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (defined PMDx bits are set to zero and unimplemented PMDx bits are set to one)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: These parameters are characterized but not tested in manufacturing.

3: Data in "Typ" column is at 3.3V, +25ºC unless otherwise stated.

TABLE 32-57: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (see Note 4) (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period	117.6	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	14 TAD		ns	
AD56	FCNV	Throughput Rate	—	—	500	Ksps	
AD57	TSAMP	Sample Time	3 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(1)	2 TAD	—	3 TAD	—	Auto-Convert Trigger not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(1)	2 TAD	—	3 TAD	—	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(1)	—	0.5 TAD	—	—	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(1)	—	—	20	μs	See **Note 3**

Note 1: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

2: These parameters are characterized but not tested in manufacturing.

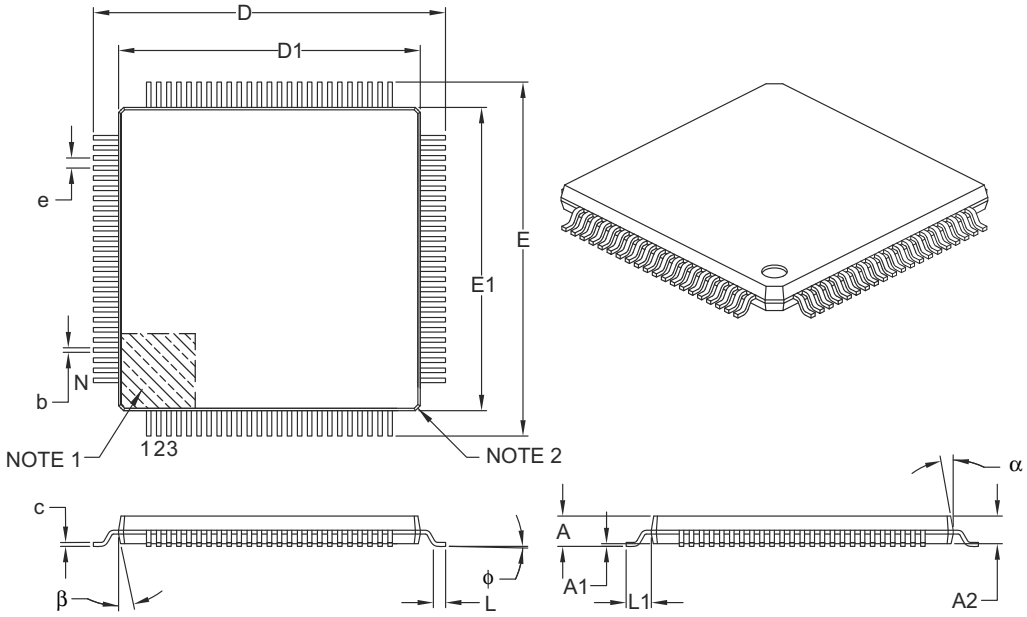
3: The tDPU parameter is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (ADxCON1<15>) = 1). During this time, the ADC result is indeterminate.

4: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules: ADC, Comparator and DAC will have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 32-11 for the minimum and maximum BOR values.

NOTES:

100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.40 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		14.00 BSC	
Overall Length	D		14.00 BSC	
Molded Package Width	E1		12.00 BSC	
Molded Package Length	D1		12.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

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